

VIA

Mobile360 M810

Fanless ultra-compact in-vehicle solution for flexible 360° SVS, ADAS and DMS configurations



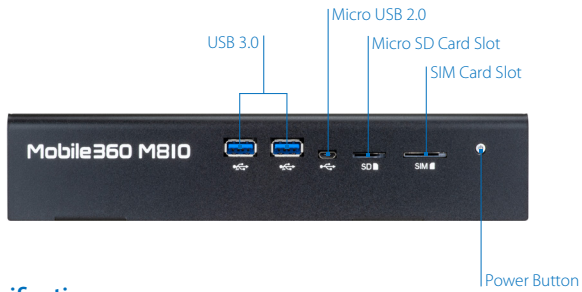
Features

- Six FAKRA connectors
- VIA ADAS, including BSD, FCW, LDW, SLD, and DMOD
- 360° real-time SVS with VIA Multi-Stitch technology
- Wi-Fi, Bluetooth 4.1 and GPS wireless connectivity
- 9~36V DC-in with IGN support & 12V/1A DC-out

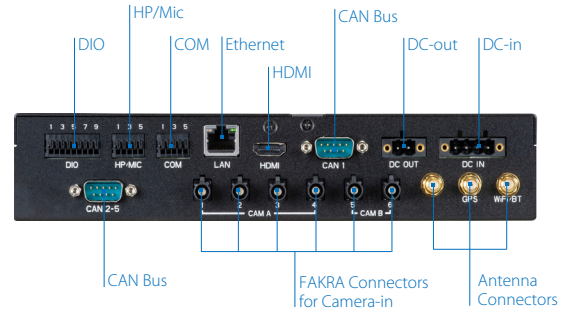
Specifications

Model Name	Mobile360 M810
Processor	Qualcomm® APQ8096A Embedded Processor - Two high-performance Kryo cores up to 2.054GHz - Two low power Kryo cores up to 1.593GHz
System Memory	4GB LPDDR4 RAM
Storage	16GB eMMC flash memory 2 M.2 SATA slots
Graphics	Qualcomm® Adreno™ 530 GPU 3D graphics accelerator with 64-bit addressing 624MHz Graphics engine supporting OpenGL ES 3.1/GEP, GL4.4, DX11.3/4, OpenCL 2.0, Renderscript-Next Supports H.264, VP8, HEVC 8/10-bit, VP9 video decoding up to: 4K@60fps, 1080p@240fps, 8 x 1080p@30fps
Camera-in Interface	2 DS90UB964-Q1 Quad FPD-Link III deserializer Hub
LAN	RTL8111G Ethernet Controller
Wireless Connectivity	AMPAK12356_I Mini PCIe WIFI/BT4.1 Module MAX-M8Q-0-10 u-blox 8 GNSS module
Audio	TI 6PAIC3104IRHBRQ1 Audio Codec
HDMI	Integrated HDMI 2.0 transmitter
Expansion I/O	1 Mini PCIe slot (USB only) for 4G Module 1 Mini PCIe slot (PCIe/USB) for WiFi/BT Module
Front Panel I/O	2 USB 3.0 ports 1 Micro USB 2.0 port (for debugging) 1 Micro SD card slot 1 SIM card slot (optional) 1 Power button
Back Panel I/O	1 HDMI port 1 DIO port 1 COM port 2 CAN bus ports (supports up to five CAN bus) 1 Gigabit Ethernet port 6 FAKRA connectors for camera-in 1 Headphone/Mic-in connector 3 Antenna connectors for Wi-Fi/BT, GPS, and 4G (factory option) 1 4-pole Phoenix 9~36V DC-in 1 2-pole Phoenix 12V DC-out
Power Supply	9~36V DC-in with IGN
Operating System	Yocto2.3
Operating Temperature	-20°C ~ 70°C
Storage Temperature	-20°C ~ 70°C
Operating Humidity	0~95% (non-condensing)
Vibration Loading During Operation	ISO-16750-3 compliance
Shock During Operation	ISO-16750-3 compliance

Front Panel External I/O



Back Panel External I/O



Specifications

Model Name	Mobile360 M810
Mechanical Construction	Metal chassis housing
Dimensions	236.7mm(W) x 46mm(H) x 180mm(D) (9.32" x 1.81" x 7.09")
Weight	2.2kg (4.85lbs)
Compliance	CE, FCC,

Ordering Information

Part Number	SoC Frequency	Description
M360-810-1Q20A1	Qualcomm® APQ8096A Embedded Processor @ 2.054GHz/1.593GHz	Fanless mobile system with 2.054GHz Qualcomm® APQ8096A Embedded Processor, 4GB LPDDR4 RAM, HDMI, 2 USB 3.0, Micro USB 2.0 (debugging), DIO, COM, 2 CAN bus, Gigabit Ethernet, 6 FAKRA connectors for camera-in, Wi-Fi, Bluetooth 4.1, GPS, Micro SD card slot, 2 M.2 slots, 12V DC-out, 9~36V DC-in with IGN

Optional Accessories

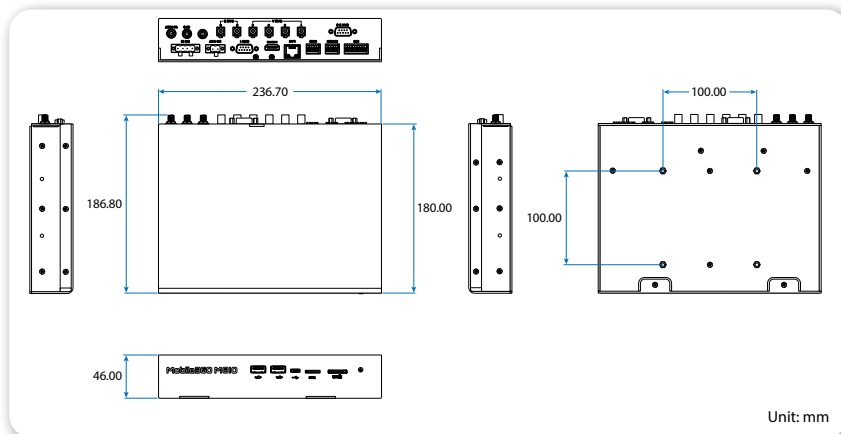
Camera & Accessories

Part Number	Description
99G40-08075Z	1.0MP FOV-40 720p CMOS automotive-grade camera
99G40-08074Z	1.0MP FOV-190 720p CMOS automotive-grade camera
99G33-230396	10M FAKRA cable
99G33-230406	15M FAKRA cable

Display Accessories

Part Number	Description
99G73-01034C	10" Resistive touch monitor (1280x800)
99G73-01030C	7" Resistive touch monitor (1280x800)

Dimensions



Packing List

Items
Mobile360 M810 system
2 Phoenix plug to DC jacks (DC-in & DC-out)
COM cable (for debugging)
GPS antenna
2 Wi-Fi/BT antennas